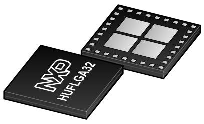


SOT2093-1

HUFLGA32, thermal enhanced ultra-thin, fine-pitched land grid array package, 32 terminals, 0.5 mm pitch, 4.5 mm x 4.5 mm x 0.46 mm body

8 December 2020 Package information

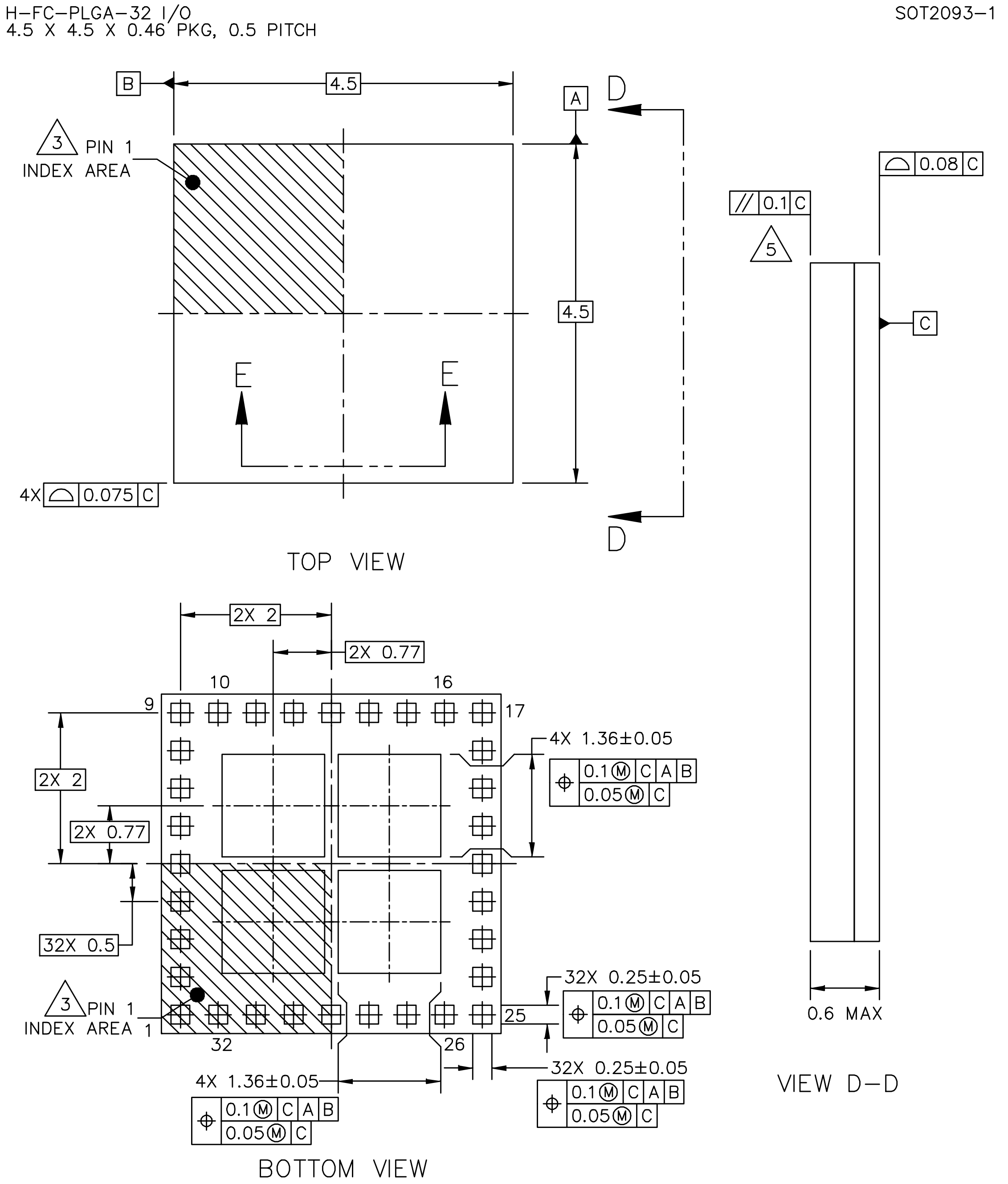
1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HUFLGA32
Package style descriptive code	UFLGA (ultra thin fine-pitch land grid array package)
Mounting method type	S (surface mount)
Issue date	09-11-2020
Manufacturer package code	98ASA01720D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.425	4.5	4.575	mm
package width	4.425	4.5	4.575	mm
package height	-	0.46	0.6	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	32	-	

2 Package outline



DATE: 09 NOV 2020

	STANDARD:	DRAWING NUMBER:	REVISION:	
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	NON JEDEC	98ASA01720D	0	

Figure 1. Package outline HUFLGA32 (SOT2093-1)

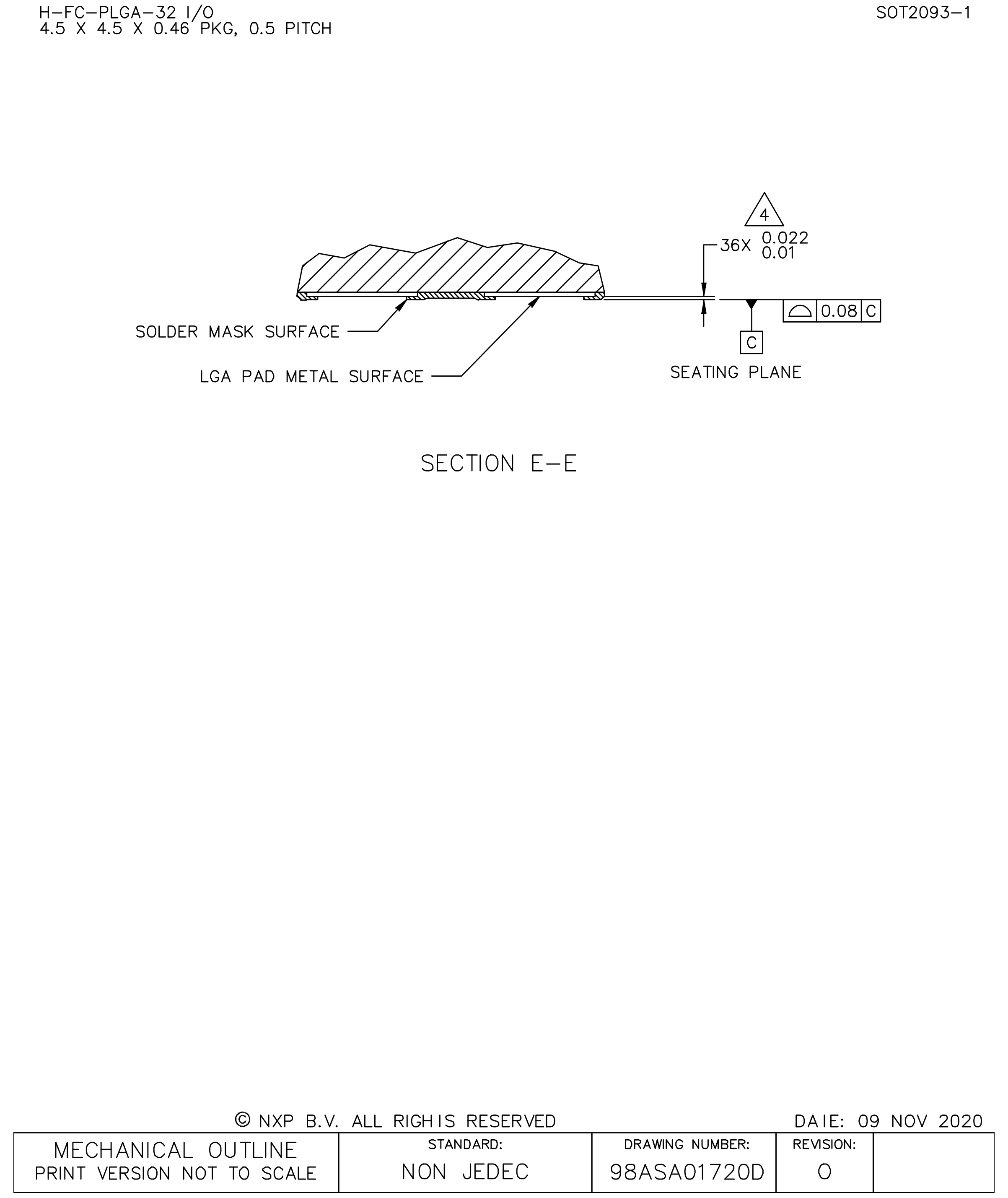
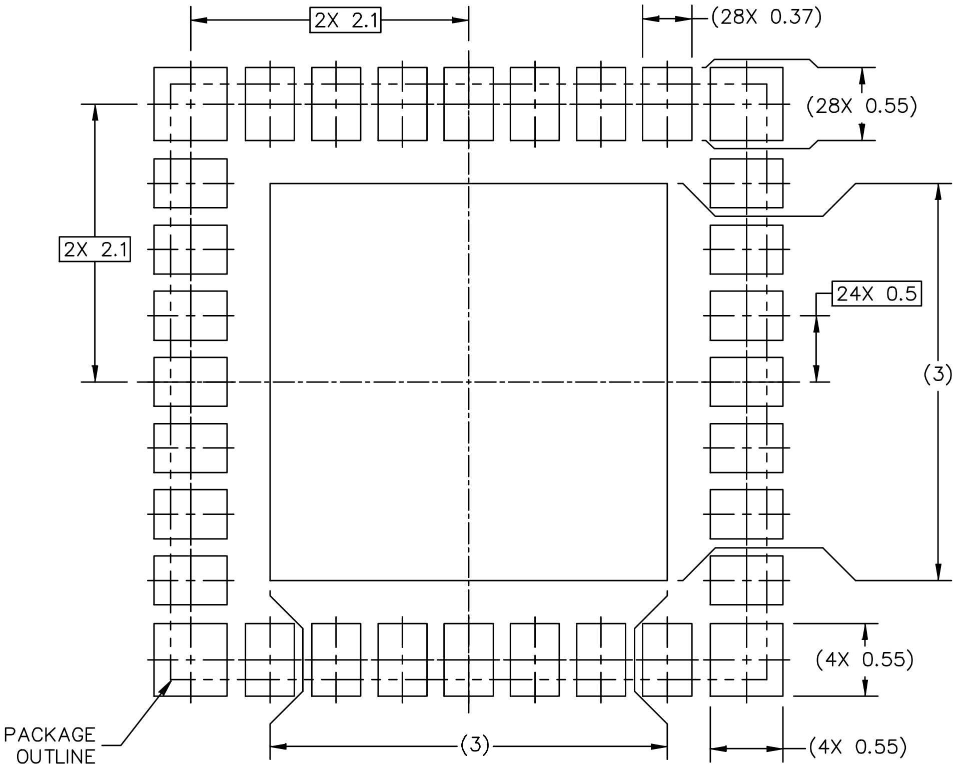


Figure 2. Package outline detail of HUFLGA32 (SOT2093-1)

3 Soldering

H–FC–PLGA–32 I/O
4.5 X 4.5 X 0.46 PKG, 0.5 PITCH

SOT2093–1



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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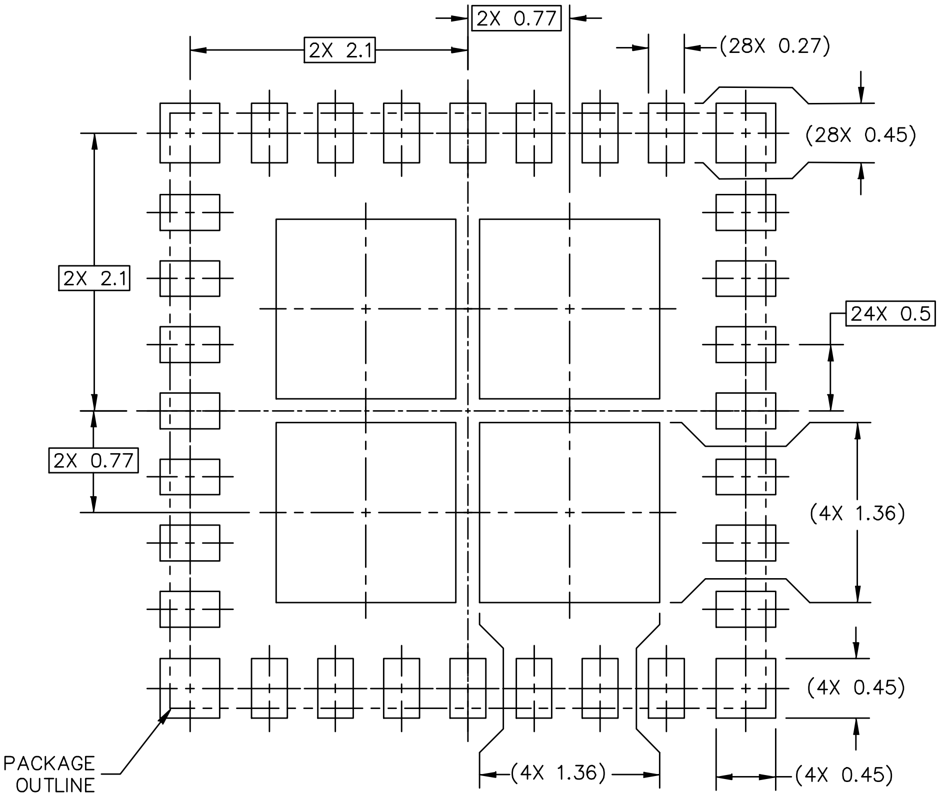
DATE: 09 NOV 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01720D	REVISION: O	

Figure 3. Reflow soldering footprint part1 for HUFLGA32 (SOT2093-1)

H-FC-PLGA-32 I/O
4.5 X 4.5 X 0.46 PKG, 0.5 PITCH

SOT2093-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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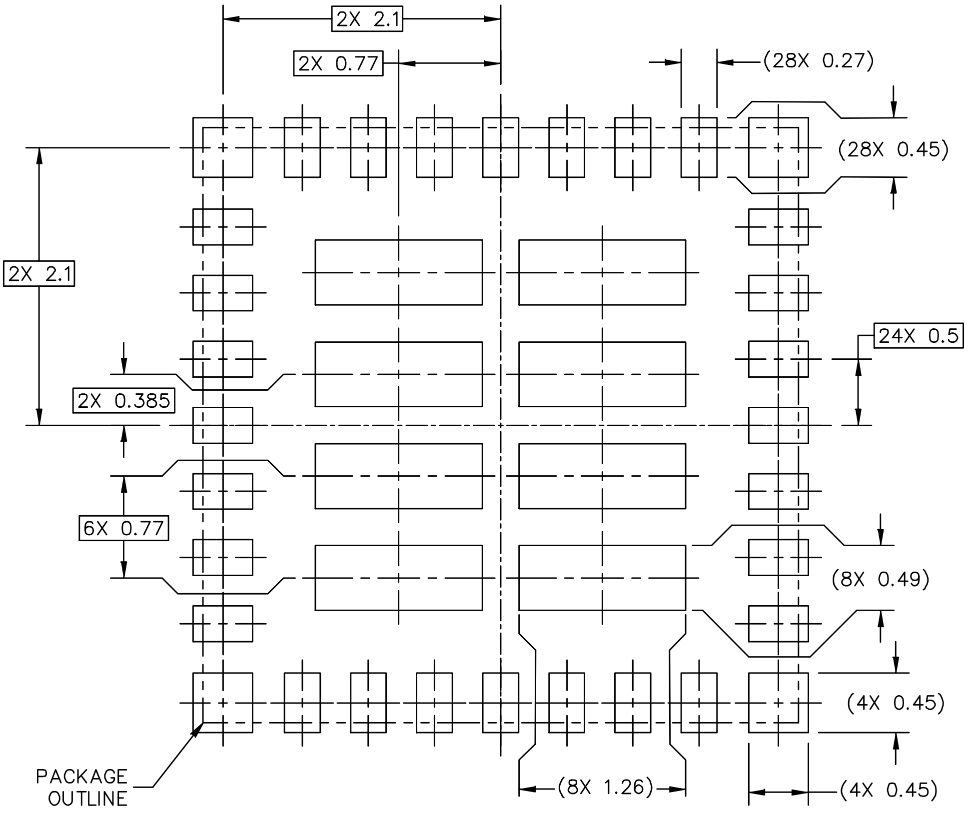
DATE: 09 NOV 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01720D	REVISION: 0	

Figure 4. Reflow soldering footprint part2 for HUFLGA32 (SOT2093-1)

H-FC-PLGA-32 I/O
4.5 X 4.5 X 0.46 PKG, 0.5 PITCH

SOT2093-1



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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DATE: 09 NOV 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01720D	REVISION: O	

Figure 5. Reflow soldering footprint part3 for HUFLGA32 (SOT2093-1)

H–FC–PLGA–32 I/O
4.5 X 4.5 X 0.46 PKG, 0.5 PITCH

SOT2093–1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS.

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DATE: 09 NOV 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01720D	REVISION: O	

Figure 6. Package outline note HUFLGA32 (SOT2093-1)

4 Legal information

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Date of release: 8 December 2020